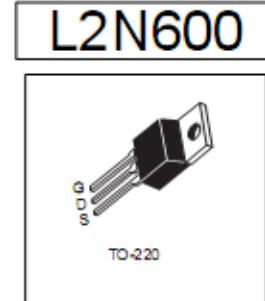


## N-Channel Enhancement Mode Field Effect Transistor

**600V N-Channel Enhancement-Mode MOSFET**

**V<sub>DS</sub> = 600V**

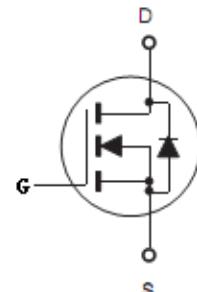
**R<sub>DS(ON)</sub>, V<sub>GS</sub>@10V, I<sub>DS</sub>@1A = 3.8**



### FEATURES

- Super high dense cell design for extremely low R<sub>DS(ON)</sub>.
- High power and current handing capability.
- Lead free product is acquired.
- TO-220 full-pak for through hole.

We declare that the material of product  
compliance with RoHS requirements.



### ABSOLUTE MAXIMUM RATINGS $T_c = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit		Units
Drain-Source Voltage	V <sub>DS</sub>	600		V
Gate-Source Voltage	V <sub>GS</sub>	$\pm 30$		V
Drain Current-Continuous	I <sub>D</sub>	2		A
Drain Current-Pulsed <sup>a</sup>	I <sub>DM</sub> <sup>b</sup>	6		A
Maximum Power Dissipation @ T <sub>C</sub> = 25°C - Derate above 25°C	P <sub>D</sub>	60		W
		0.48		W/°C
Single Pulsed Avalanche Energy <sup>d</sup>	E <sub>AS</sub>	125		mJ
Repetitive Avalanche Current <sup>e</sup>	I <sub>AR</sub>	2		A
Repetitive Avalanche Energy <sup>e</sup>	E <sub>AR</sub>	5.4		mJ
Operating and Store Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150		°C

### Thermal Characteristics

Parameter	Symbol	Limit		Units
Thermal Resistance, Junction-to-Case	R <sub>JC</sub>	2.1	4.3	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>JA</sub>	62.5	65	°C/W

# L2N600

## Electrical Characteristics $T_C = 25 \text{ C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	600			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 600\text{V}, V_{GS} = 0\text{V}$			25	$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{GSSF}$	$V_{GS} = 30\text{V}, V_{DS} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	$I_{GSSR}$	$V_{GS} = -30\text{V}, V_{DS} = 0\text{V}$			-100	nA
<b>On Characteristics<sup>b</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	2		4	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{V}, I_D = 1\text{A}$		3.8	5.0	$\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS} = 50\text{V}, I_D = 1\text{A}$		1.2		S
<b>Dynamic Characteristics<sup>c</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}, f = 1.0 \text{ MHz}$		250		pF
Output Capacitance	$C_{oss}$			50		pF
Reverse Transfer Capacitance	$C_{rss}$			30		pF
<b>Switching Characteristics<sup>c</sup></b>						
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 300\text{V}, I_D = 2\text{A}, V_{GS} = 10\text{V}, R_{GEN} = 18\Omega$		18	35	ns
Turn-On Rise Time	$t_r$			18	35	ns
Turn-Off Delay Time	$t_{d(off)}$			50	90	ns
Turn-Off Fall Time	$t_f$			16	40	ns
Total Gate Charge	$Q_g$	$V_{DS} = 480\text{V}, I_D = 2\text{A}, V_{GS} = 10\text{V}$		20	25	nC
Gate-Source Charge	$Q_{gs}$			2		nC
Gate-Drain Charge	$Q_{gd}$			12		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_S$ <sup>g</sup>				2	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{SD}$	$V_{GS} = 0\text{V}, I_S = 2\text{A}$ <sup>h</sup>			1.5	V

### Notes :

a.Repetitive Rating : Pulse width limited by maximum junction temperature .

b.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$  .

c.Guaranteed by design, not subject to production testing.

d. $L_s = 60\text{mH}, I_{AS} = 2.0\text{A}, V_{DD} = 50\text{V}, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$  .

e.Limited only by maximum temperature allowed .

f.Pulse width limited by safe operating area .

g.Full package  $I_{S(max)} = 1.5\text{A}$  .

h.Full package  $V_{SD}$  test condition  $I_S = 1.5\text{A}$  .

## L2N600

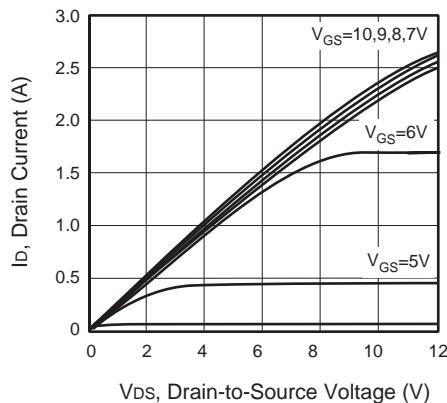


Figure 1. Output Characteristics

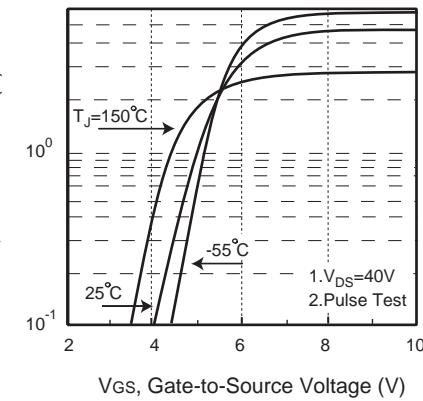


Figure 2. Transfer Characteristics

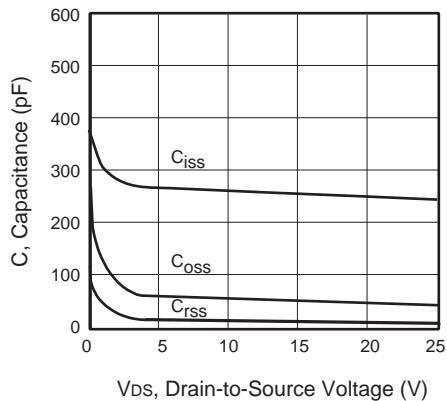


Figure 3. Capacitance

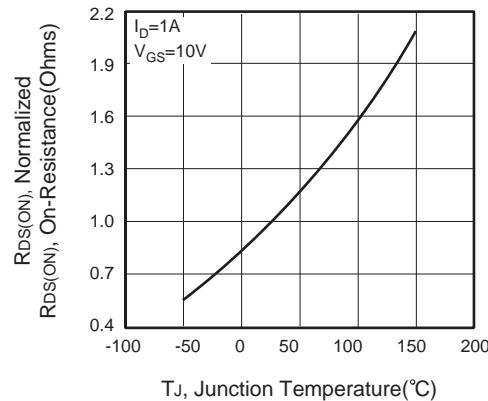


Figure 4. On-Resistance Variation with Temperature

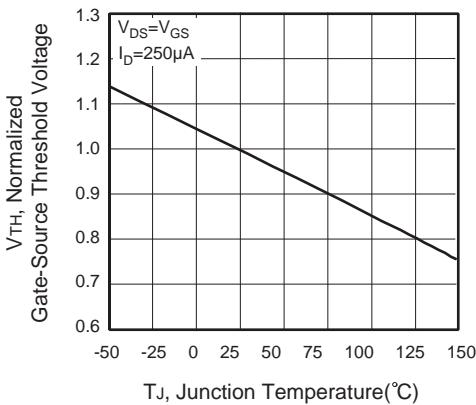


Figure 5. Gate Threshold Variation with Temperature

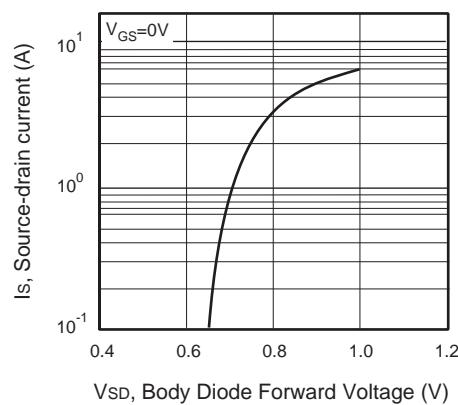
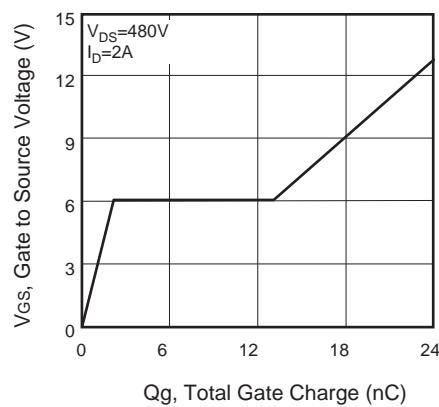
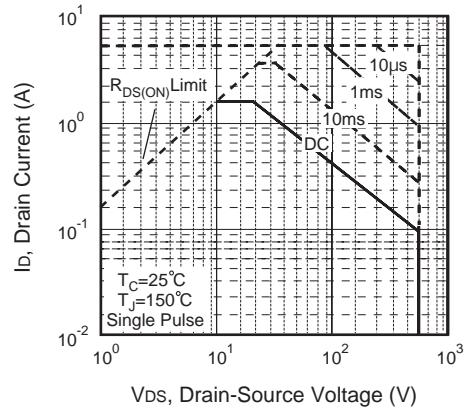


Figure 6. Body Diode Forward Voltage Variation with Source Current

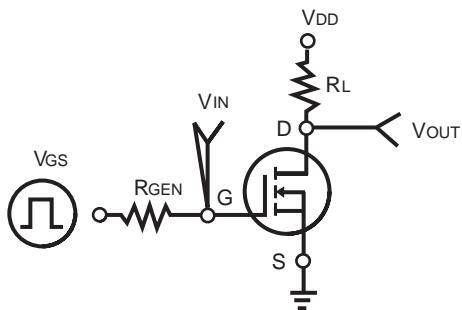
# L2N600



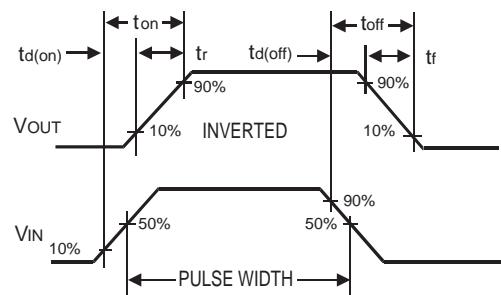
**Figure 7. Gate Charge**



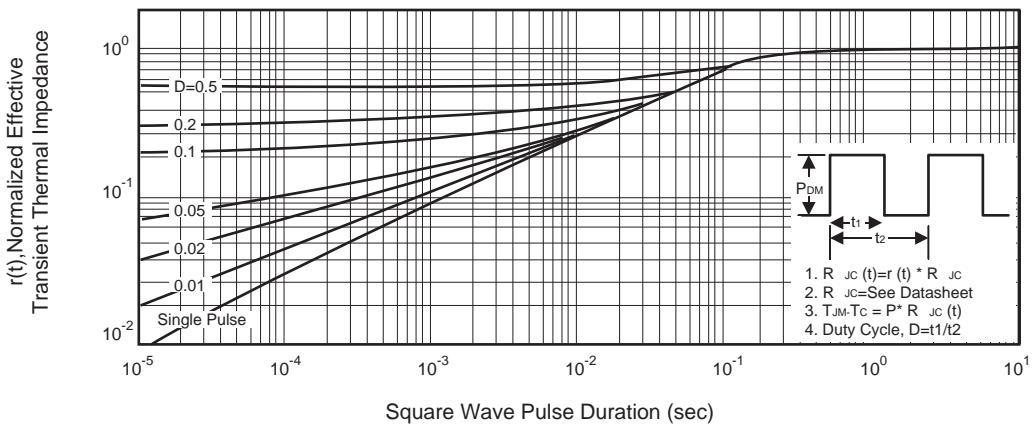
**Figure 8. Maximum Safe Operating Area**



**Figure 9. Switching Test Circuit**

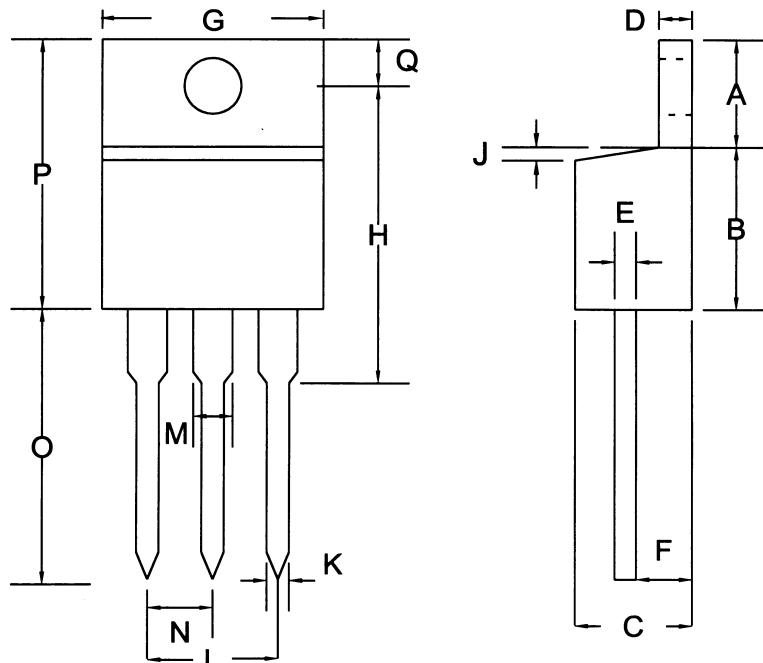


**Figure 10. Switching Waveforms**



**Figure 11. Normalized Thermal Transient Impedance Curve**

# L2N600



Symbol	Dimensions In Millimeters			Dimensions In Inches		
	Min	Nom	Max	Min	Nom	Max
A	5.58	6.54	7.49	0.220	0.257	0.295
B	8.38	8.64	8.90	0.330	0.340	0.350
C	4.07	4.45	4.82	0.160	0.175	0.190
D	1.15	1.27	1.39	0.045	0.050	0.055
E	0.35	0.45	0.60	0.014	0.018	0.024
F	2.04	2.42	2.79	0.080	0.095	0.110
G	9.66	9.97	10.28	0.380	0.393	0.405
H	—	16.25	—	—	0.640	—
I	3.68	3.83	3.98	0.145	0.151	0.157
J	—	—	1.27	—	—	0.050
K	0.75	0.85	0.95	0.030	0.033	0.037
L	4.83	5.08	5.33	0.190	0.200	0.210
M	1.15	1.33	1.52	0.045	0.052	0.060
N	2.42	2.54	2.66	0.095	0.100	0.105
O	12.70	13.48	14.27	0.500	0.531	0.562
P	14.48	15.17	15.87	0.570	0.597	0.625
Q	2.54	2.79	3.04	0.100	0.110	0.120